# MSD602-RT1G

# **General Purpose NPN Amplifier Transistor**

### Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and **PPAP** Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

### **MAXIMUM RATINGS** ( $T_A = 25^{\circ}C$ )

Rating	Symbol	Value	Unit
Collector-Base Voltage	V <sub>(BR)CBO</sub>	60	Vdc
Collector–Emitter Voltage	V <sub>(BR)CEO</sub>	50	Vdc
Emitter-Base Voltage	V <sub>(BR)EBO</sub>	7.0	Vdc
Collector Current – Continuous	۱ <sub>C</sub>	500	mAdc
Collector Current – Peak	I <sub>C(P)</sub>	1.0	Adc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Power Dissipation	PD	200	mW
Junction Temperature	TJ	150	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +150	°C

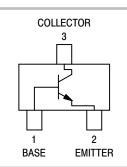
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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### MARKING DIAGRAM



WR = Specific Device Code Μ

= Date Code

= Pb-Free Package . (Note: Microdot may be in either location)

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MSD-602RT1G	SC–59 (Pb–Free)	3,000 / Tape & Reel
SMSD-602RT1G	SC–59 (Pb–Free)	3,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

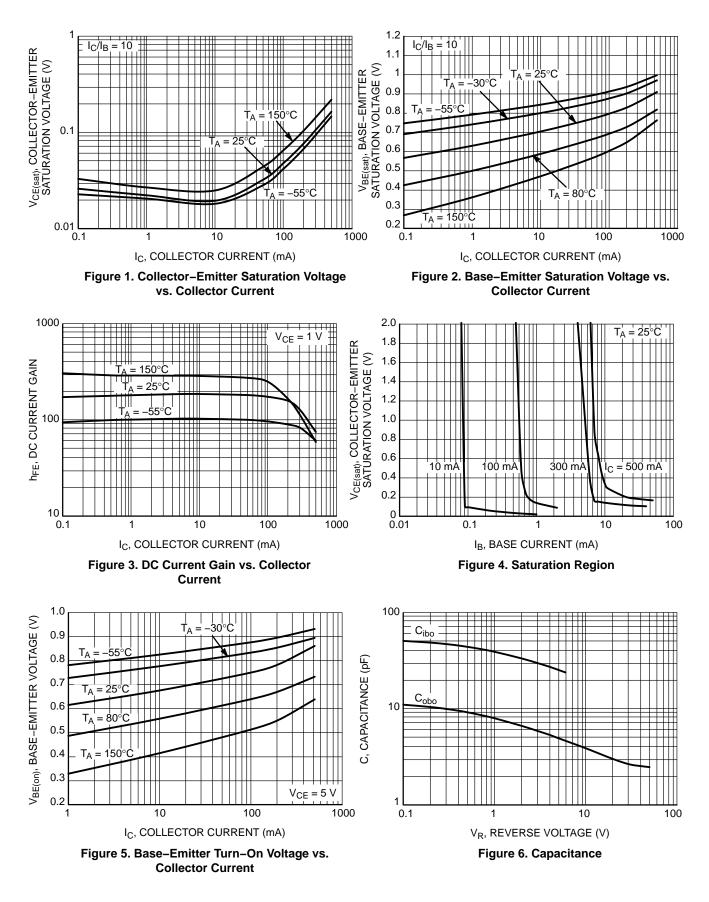
# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = $25^{\circ}$ C)

Characteristic	Symbol	Min	Max	Unit
Collector–Emitter Breakdown Voltage $(I_C = 10 \text{ mA}, I_B = 0)$	V <sub>(BR)</sub> CEO	50	_	V
Collector–Base Breakdown Voltage $(I_C = 10 \ \mu A, I_E = 0)$	V <sub>(BR)</sub> CBO	60	-	V
Emitter–Base Breakdown Voltage $(I_E = 10 \ \mu A, I_C = 0)$	V <sub>(BR)EBO</sub>	7.0	-	V
Collector–Base Cutoff Current $(V_{CB} = 20 \text{ V}, I_E = 0)$	I <sub>CBO</sub>	_	0.1	μΑ
DC Current Gain (Note 1) ( $V_{CE} = 10 \text{ V}, I_C = 150 \text{ mA}$ ) ( $V_{CE} = 10 \text{ V}, I_C = 500 \text{ mA}$ )	h <sub>FE1</sub> h <sub>FE2</sub>	120 40	240 _	_
Collector–Emitter Saturation Voltage $(I_C = 300 \text{ mA}, I_B = 30 \text{ mA})$	V <sub>CE(sat)</sub>	_	0.6	V
Base–Emitter On Voltage ( $I_C = 300 \text{ mA}, V_{CE} = 5 \text{ V}$ )	V <sub>BE(on)</sub>	-	1.0	V
Base–Emitter Saturation Voltage $(I_C = 300 \text{ mA}, I_B = 30 \text{ mA})$	V <sub>BE(sat)</sub>	_	1.0	V
Output Capacitance $(V_{CB} = 10 \text{ V}, I_E = 0, f = 1.0 \text{ MHz})$	C <sub>ob</sub>	_	15	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width  $\leq$  300 µs, D.C.  $\leq$  2%.

### MSD602-RT1G

### **TYPICAL CHARACTERISTICS**



## MSD602-RT1G

### **TYPICAL CHARACTERISTICS**

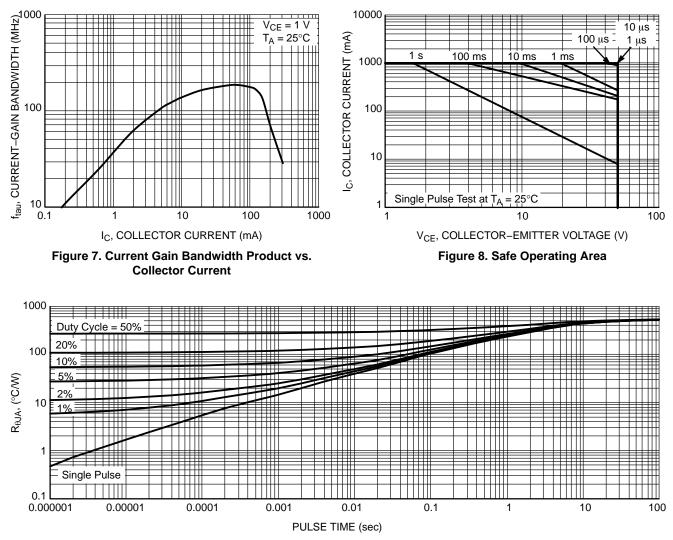


Figure 9. Thermal Response





SCALE 2:1



### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NOTES:

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.15	1.30	0.039	0.045	0.051
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.35	0.43	0.50	0.014	0.017	0.020
С	0.09	0.14	0.18	0.003	0.005	0.007
D	2.70	2.90	3.10	0.106	0.114	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
е	1.70	1.90	2.10	0.067	0.075	0.083
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.80	3.00	0.099	0.110	0.118

#### GENERIC **MARKING DIAGRAM**



= Specific Device Code XXX Μ = Date Code

= Pb-Free Package\*

(\*Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. BASE	PIN 1. ANODE	PIN 1. ANODE
2. EMITTER	2. N.C.	2. ANODE
3. COLLECTOR	3. CATHODE	3. CATHODE
Style 4:	Style 5:	STYLE 6:
Pin 1. Cathode	Pin 1. Cathode	PIN 1. ANODE
2. N.C.	2. Cathode	2. CATHODE
3. Anode	3. Anode	3. ANODE/CATHODE

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